

IEEE TRANSACTIONS ON COMPONENTS PACKAGING AND MANUFACTURING TECHNOLOGY

CPMT SOCIETY BOARD OF GOVERNORS

President

S. W. RICKY LEE
Hong Kong University of
Science & Technology
Clear Water Bay, Kowloon, Hong Kong
rickylee@ust.hk

Vice President, (Publications)

R. WAYNE JOHNSON
Auburn University
Auburn, AL, USA
johnson@eng.auburn.edu

Vice President, (Technical)

JIE XUE
Cisco Systems
San Jose, CA, USA
jixue@cisco.com

Vice President, (Education)

KITTY PEARSALL
IBM
Austin, TX, USA
kittyp@us.ibm.com

Vice President, (Conferences)

JEAN TREWHELLA
IBM
Hopewell Junction, NY, USA
jeanmh@us.ibm.com

Vice President, (Finance)

THOMAS G. REYNOLDS, III
Niceville, FL, USA
t.reynolds@ieee.org

Elected Members-at-Large

Through 2012

C. BAILEY
D. DONAHOE
P. D. FRANZON

D. LU
K.-L. LIN
L. W. SCHAPER

Through 2013

D. MALLIK
T. MATTILA
J. E. MORRIS

E. PERFECTO
D. SHANGGUAN
G. POUPON

Through 2014

M. AOYAGI
A. BAR-COHEN
D. R. EDWARDS

B. KESER
M. PAULASTO-KRÖCKEL
CP WONG

CPMT Executive Office

MARSHA TICKMAN, *Executive Director*
445 Hoes Lane
Piscataway, NJ +1 732-562-5529
m.tickman@ieee.org

Ex Officio

WILLIAM T. CHEN, *Senior Past President*
ROLF ASCHENBRENNER, *Junior Past President*

Strategic Program Directors 2012–2013

Global Chapters and Membership: E. PERFECTO
Student Programs: C. BAILEY
Industry Programs: P. E. GARROU
Region 8 Programs: T. MATTILA
Region 10 Programs: K.-L. LIN

Standing Committees 2012–2013

Awards & Recognitions: P. THOMPSON
Fellows Search & Evaluation: C. P. WONG
Long Range Planning & Bylaws: W. T. CHEN
Nominations: R. ASCHENBRENNER

Technical Committees

Electrical Contacts, Connectors, and Cable: J. WITTER
IC and Package Assembly: M. GOETZ
Materials: R. CHANCHANI
High Density PWB Packaging: K. YOKOUCHI
Environmental Stress and Reliability Test: J. PROULX
Thermal Management and Thermomechanical Design: T. MAK
Fiber Optics and Photonics: VACANT
Electrical Test: B. KIM

Electrical Design, Modeling, and Simulation: M. SWAMINATHAN
Power Electronic Packaging (joint with Power Electronics Society): D. HOPKINS
Systems Packaging (joint with Computer Society): VACANT
RF and Wireless: C. GAW
MEMS and Sensor Packaging: E. JUNG
Wafer Level Packaging: M. TOEPPER
Education: R. TUMMALA
Green Electronics, Manufacturing and Packaging: N. NISSEN
Nanopackaging: R. TUMMALA

Chapters

Belarus	Germany	Oregon	Santa Clara Valley	Texas (Austin)
Binghamton	Hong Kong	Orlando	Singapore	Tokyo
Boston	Hungary/Romania	Ottawa	Saratov (Russia)	Toronto
Bulgaria	Malaysia	Philadelphia	Siberia (Russia)	United Kingdom & Republic of Ireland
Chicago	Nizhny (Russia)	Phoenix	Sweden	West Ukraine (Lviv)
Eastern North Carolina	Novosibirsk (Russia)	Pittsburgh	Switzerland	Ukraine West
Finland	Orange County	Poland	Taipei	Ukraine (Kiev)
France		San Diego		Vancouver

IEEE Officers

GORDON W. DAY, *President*
PETER W. STAECKER, *President-Elect*
CELIA L. DESMOND, *Secretary*
HAROLD L. FLESCHER, *Treasurer*
MOSHE KAM, *Past President*

MICHAEL R. LIGHTNER, *Vice President, Educational Activities*
DAVID A. HODGES, *Vice President, Publication Services and Products*
HOWARD E. MICHEL, *Vice President, Member and Geographic Activities*
STEVE M. MILLS, *President, Standards Association*
FREDERICK C. MINTZER, *Vice President, Technical Activities*
JAMES M. HOWARD, *President, IEEE-USA*

J. KEITH NELSON, *Director, Division II*

IEEE Executive Staff

DR. E. JAMES PRENDERGAST, *Executive Director & Chief Operating Officer*

THOMAS SIEGERT, *Business Administration*
MATTHEW LOEB, *Corporate Activities*
DOUGLAS GORHAM, *Educational Activities*
EILEEN M. LACH, *General Counsel & Corporate Compliance Officer*
BETSY DAVIS, SPHR, *Human Resources*
CHRIS BRANTLEY, *IEEE-USA*

ALEXANDER PASIK, *Information Technology*
PATRICK MAHONEY, *Marketing*
CECELIA JANKOWSKI, *Member and Geographic Activities*
ANTHONY DURNIAK, *Publications Activities*
JUDITH GORMAN, *Standards Activities*
MARY WARD-CALLAN, *Technical Activities*

IEEE Periodicals

Transactions/Journals Department

Staff Director: FRAN ZAPPULLA
Editorial Director: DAWN MELLEY *Production Director:* PETER M. TUOHY
Managing Editor: JEFFREY E. CICHOCKI *Journals Coordinator:* PATRICK J. KEMPF